

# FAN7390

## High-Current, High & Low-Side, Gate-Drive IC

### Features

- Floating Channels for Bootstrap Operation to +600V
- Typically 4.5A/4.5A Sourcing/Sinking Current Driving Capability
- Common-Mode dv/dt Noise Canceling Circuit
- Built-in Under-Voltage Lockout for Both Channels
- Matched Propagation Delay for Both Channels
- Logic ( $V_{SS}$ ) and Power (COM) Ground +/- 7V Offset
- 3.3V and 5V Input Logic Compatible
- Output In-phase with Input

### Applications

- PDP Sustain Driver
- HID Lamp Ballast
- SMPS
- Motor Driver

### Description

The FAN7390 is a monolithic high- and low-side gate-drive IC, which can drive high speed MOSFETs and IGBTs that operate up to +600V. It has a buffered output stage with all NMOS transistors designed for high pulse current driving capability and minimum cross-conduction.

Fairchild's high-voltage process and common-mode noise canceling techniques provide stable operation of the high-side driver under high dv/dt noise circumstances. An advanced level shift circuit offers high-side gate driver operation up to  $V_S = -9.8V$  (typical) for  $V_{BS} = 15V$ .

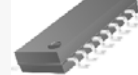
The UVLO circuit prevents malfunction when  $V_{DD}$  and  $V_{BS}$  are lower than the specified threshold voltage.

The high current and low output voltage drop feature make this device suitable for the PDP sustain pulse driver, motor driver, switching power supply, and high-power DC-DC converter applications.

8-SOP



14-SOP



### Ordering Information

Part Number	Package	Operating Temperature Range	Packing Method
FAN7390MX	8-SOP	-40°C ~ 125°C	Tape & Reel
FAN7390M1X	14-SOP		Tape & Reel

Typical Application Circuit

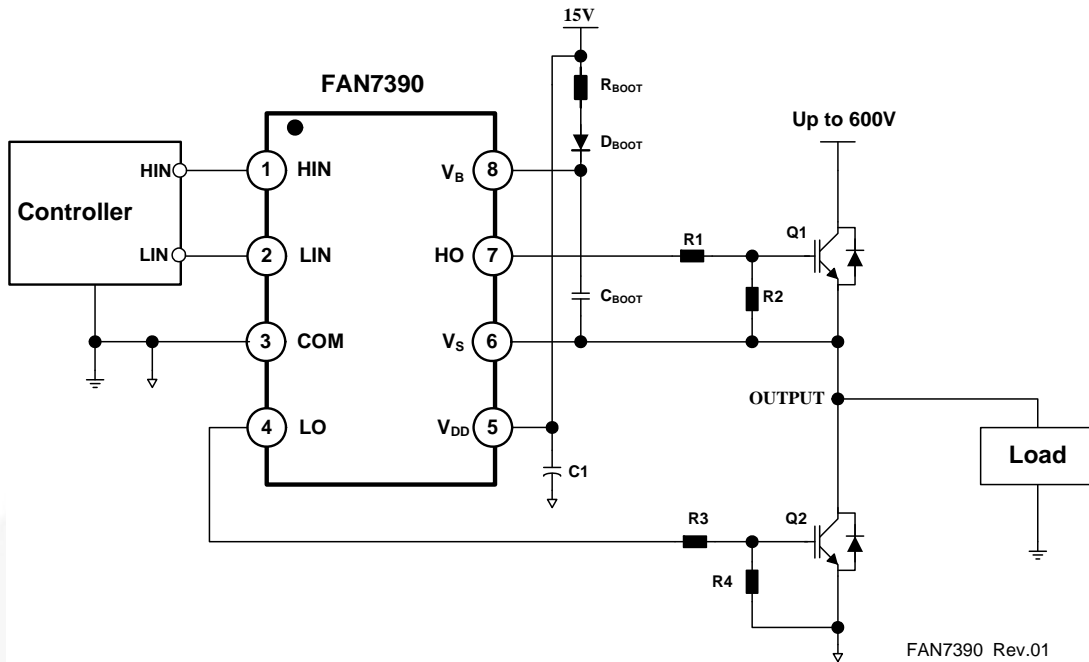


Figure 1. Application Circuit for Half-Bridge (Referenced 8-SOP)

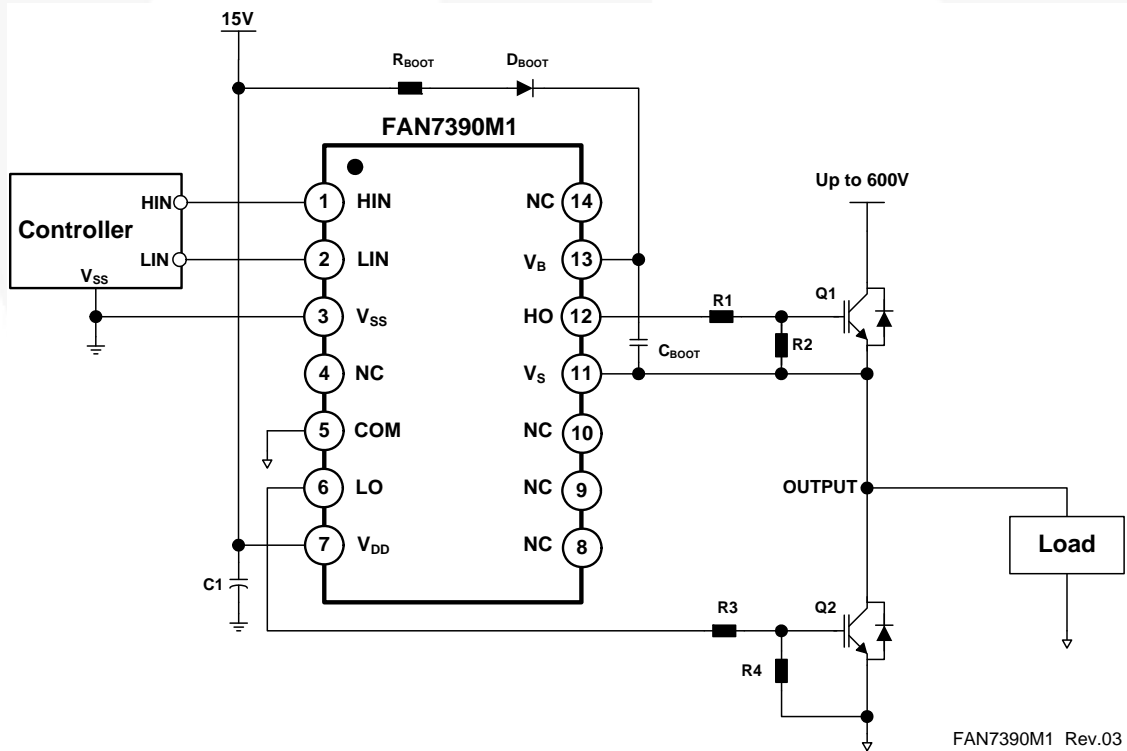


Figure 2. Application Circuit for Half-Bridge (Referenced 14-SOP)

Internal Block Diagram

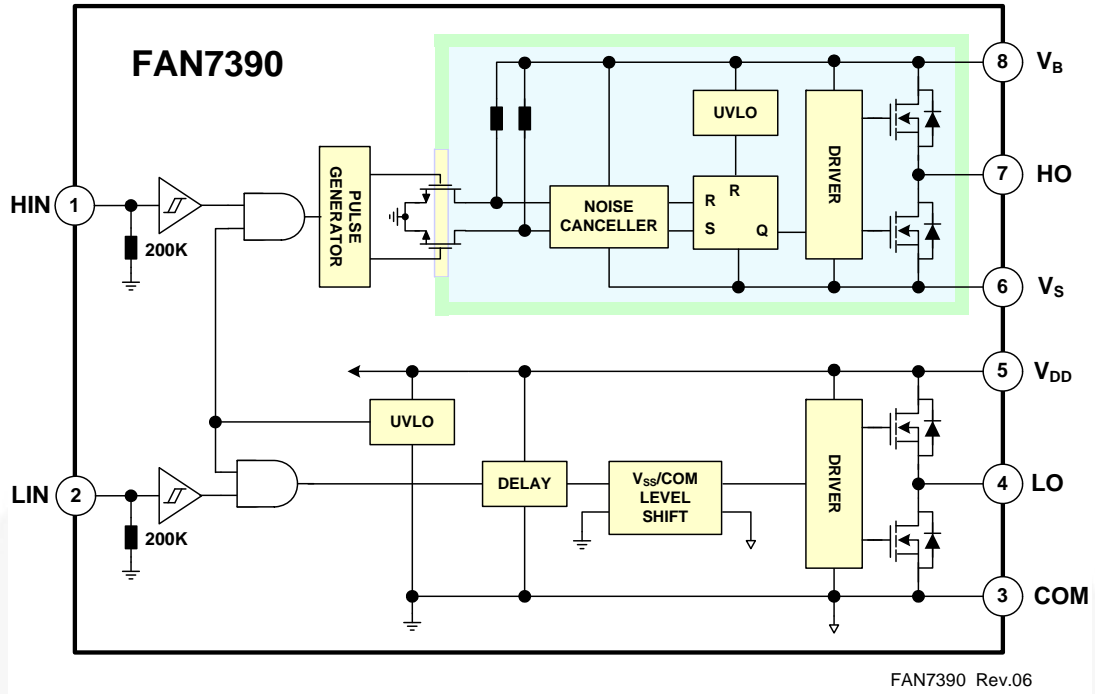


Figure 3. Functional Block Diagram (Referenced 8-SOP)

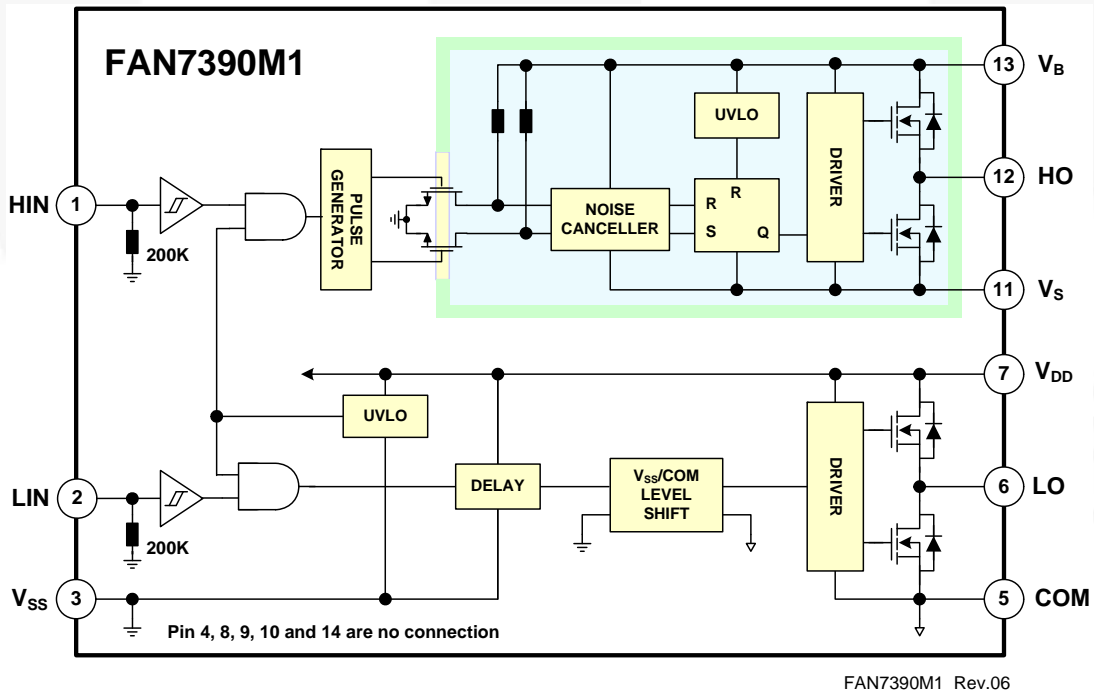


Figure 4. Functional Block Diagram (Referenced 14-SOP)

## Pin Configurations

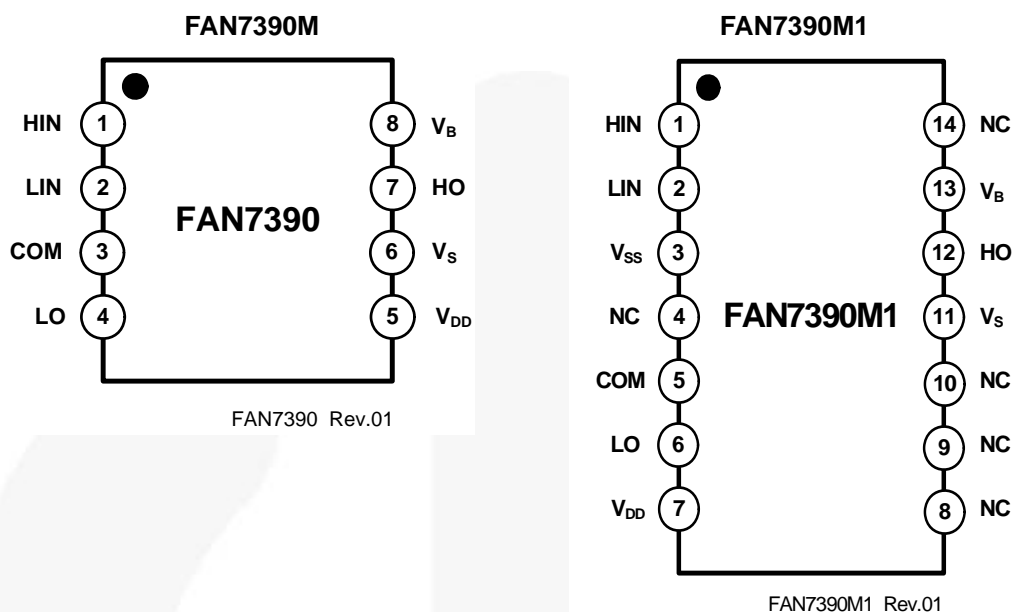


Figure 5. Pin Assignments (Top View)

## Pin Definitions

8-Pin	14-Pin	Name	Description
1	1	HIN	Logic Input for High-Side Gate Driver Output
2	2	LIN	Logic Input for Low-Side Gate Driver Output
	3	V <sub>SS</sub>	Logic Ground (FAN7390M1 only)
3	5	COM	Low-Side Driver Return
4	6	LO	Low-Side Driver Output
5	7	V <sub>DD</sub>	Low-Side and Logic Part Supply Voltage
6	11	V <sub>S</sub>	High-Voltage Floating Supply Return
7	12	HO	High-Side Driver Output
8	13	V <sub>B</sub>	High-Side Floating Supply
	4, 8, 9, 10, 14	NC	No Connect

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.  $T_A=25^{\circ}\text{C}$ , unless otherwise specified.

Symbol	Characteristics	Min.	Max.	Unit
$V_S$	High-Side Floating Supply Offset Voltage	$V_B-25$	$V_B+0.3$	V
$V_B$	High-Side Floating Supply Voltage	-0.3	625.0	V
$V_{HO}$	High-Side Floating Output Voltage HO	$V_S-0.3$	$V_B+0.3$	V
$V_{DD}$	Low-Side and Logic Fixed Supply Voltage	-0.3	25.0	V
$V_{LO}$	Low-Side Output Voltage LO	-0.3	$V_{DD}+0.3$	V
$V_{IN}$	Logic Input Voltage (HIN and LIN)	$V_{SS}-0.3$	$V_{DD}+0.3$	V
$V_{SS}$	Logic Ground (FAN7390M1 only)	$V_{DD}-25$	$V_{DD}+0.3$	V
$dV_S/dt$	Allowable Offset Voltage Slew Rate		50	V/ns
$P_D^{(1)(2)(3)}$	Power Dissipation	8-SOP	0.625	W
		14-SOP	1.000	
$\theta_{JA}$	Thermal Resistance, Junction-to-Ambient	8-SOP	200	$^{\circ}\text{C/W}$
		14-SOP	110	
$T_J$	Junction Temperature		+150	$^{\circ}\text{C}$
$T_{STG}$	Storage Temperature		+150	$^{\circ}\text{C}$

### Notes:

- Mounted on 76.2 x 114.3 x 1.6mm PCB (FR-4 glass epoxy material).
- Refer to the following standards:
  - JESD51-2: Integral circuits thermal test method environmental conditions - natural convection
  - JESD51-3: Low effective thermal conductivity test board for leaded surface mount packages
- Do not exceed  $P_D$  under any circumstances.

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Unit
$V_B$	High-Side Floating Supply Voltage	$V_S+10$	$V_S+22$	V
$V_S$	High-Side Floating Supply Offset Voltage	$6-V_{DD}$	600	V
$V_{HO}$	High-Side Output Voltage	$V_S$	$V_B$	V
$V_{DD}$	Low-Side and Logic Supply Voltage	10	22	V
$V_{LO}$	Low-Side Output Voltage	COM	$V_{DD}$	V
$V_{IN}$	Logic Input Voltage (HIN and LIN)	$V_{SS}$	$V_{DD}$	V
$T_A$	Operating Ambient Temperature	-40	+125	$^{\circ}\text{C}$

## Electrical Characteristics

$V_{BIAS}$  ( $V_{DD}$ ,  $V_{BS}$ )=15.0V,  $V_S=V_{SS}=COM$ ,  $T_A=25^\circ C$ , unless otherwise specified. The  $V_{IL}$ ,  $V_{IH}$ , and  $I_{IN}$  parameters are referenced to  $V_{SS}/COM$  and are applicable to the respective input signals HIN and LIN. The  $V_O$  and  $I_O$  parameters are referenced to COM and  $V_S$  is applicable to the respective output signals HO and LO.

Symbol	Characteristics	Test Condition	Min.	Typ.	Max.	Unit
<b>POWER SUPPLY SECTION (<math>V_{DD}</math> AND <math>V_{BS}</math>)</b>						
$V_{DDUV+}$ $V_{BSUV+}$	$V_{DD}$ and $V_{BS}$ Supply Under-Voltage Positive-going Threshold		8.0	8.8	9.8	V
$V_{DDUV-}$ $V_{BSUV-}$	$V_{DD}$ and $V_{BS}$ Supply Under-Voltage Negative-going Threshold		7.4	8.3	9.0	
$V_{DDUVH}$ $V_{BSUVH}$	$V_{DD}$ and $V_{BS}$ Supply Under-Voltage Lockout Hysteresis Voltage			0.5		
$I_{LK}$	Offset Supply Leakage Current	$V_B=V_S=600V$			50	$\mu A$
$I_{QBS}$	Quiescent $V_{BS}$ Supply Current	$V_{IN}=0V$ or $5V$		45	80	
$I_{QDD}$	Quiescent $V_{DD}$ Supply Current	$V_{IN}=0V$ or $5V$		75	110	
$I_{PBS}$	Operating $V_{BS}$ Supply Current	$f_{IN}=20kHz$ , rms value		530	640	$\mu A$
$I_{PDD}$	Operating $V_{DD}$ Supply Current	$f_{IN}=20kHz$ , rms value		530	640	
<b>LOGIC INPUT SECTION (HIN, LIN)</b>						
$V_{IH}$	Logic "1" Input Voltage		2.5			V
$V_{IL}$	Logic "0" Input Voltage				1.2	
$I_{IN+}$	Logic "1" Input Bias Current	$V_{IN}=5V$		25	50	$\mu A$
$I_{IN-}$	Logic "0" Input Bias Current	$V_{IN}=0V$		1.0	2.0	
$R_{IN}$	Input Pull-down Resistance		100	200		$K\Omega$
<b>GATE DRIVER OUTPUT SECTION (HO, LO)</b>						
$V_{OH}$	High-level Output Voltage, $V_{BIAS}-V_O$	No Load			1.0	V
$V_{OL}$	Low-level Output Voltage, $V_O$	No Load			35	mV
$I_{O+}$	Output High, Short-circuit Pulsed Current <sup>(4)</sup>	$V_O=0V$ , $V_{IN}=5V$ with $PW<10\mu s$	3.5	4.5		A
$I_{O-}$	Output Low, Short-circuit Pulsed Current <sup>(4)</sup>	$V_O=15V$ , $V_{IN}=0V$ with $PW<10\mu s$	3.5	4.5		
$V_S$	Allowable Negative $V_S$ Pin Voltage for HIN Signal Propagation to HO			-9.8	-7.0	V
$V_{SS-COM}$	$V_{SS}-COM/COM-V_{SS}$ Voltage Endurability		-7.0		7.0	V

### Note:

4. This parameter guaranteed by design.

## Dynamic Electrical Characteristics

$V_{BIAS}$  ( $V_{DD}$ ,  $V_{BS}$ )=15.0V,  $V_S=V_{SS}=COM=0V$ ,  $C_L=1000pF$  and  $T_A=25^\circ C$  unless otherwise specified.

Symbol	Characteristics	Test Condition	Min.	Typ.	Max.	Unit
$t_{on}$	Turn-on Propagation Delay	$V_S=0V$		140	200	ns
$t_{off}$	Turn-off Propagation Delay	$V_S=0V$		140	200	
MT	Delay Matching, HS & LS Turn-on/off			0	50	
$t_r$	Turn-on Rise Time			25	50	
$t_f$	Turn-off Fall Time			20	45	

## Typical Characteristics

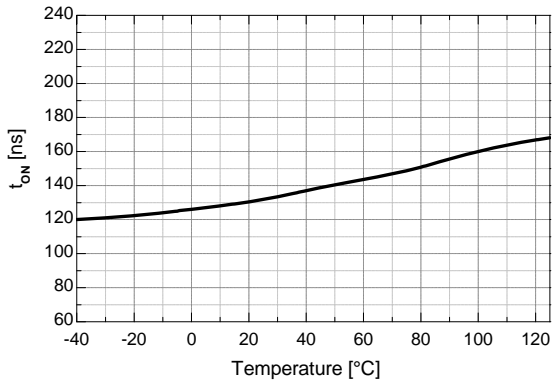


Figure 6. Turn-on Propagation Delay vs. Temperature

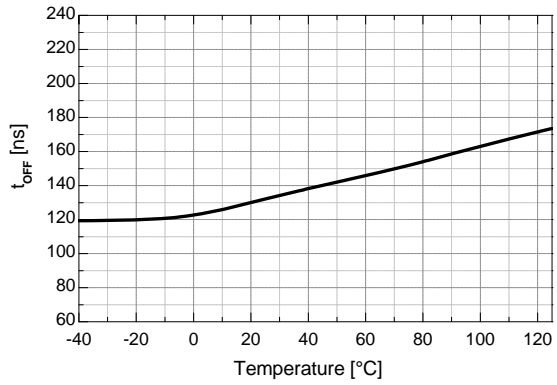


Figure 7. Turn-off Propagation Delay vs. Temperature

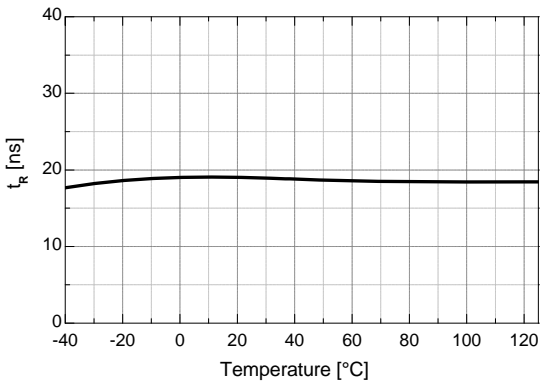


Figure 8. Turn-on Rise Time vs. Temperature

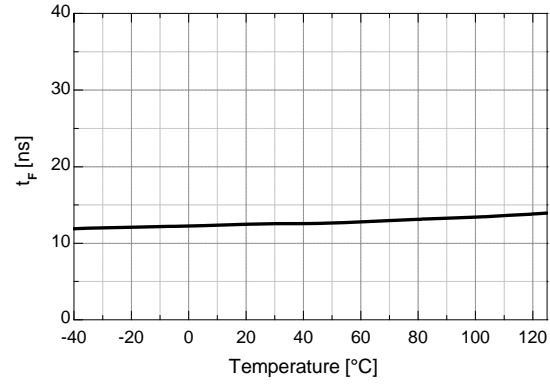


Figure 9. Turn-off Fall Time vs. Temperature

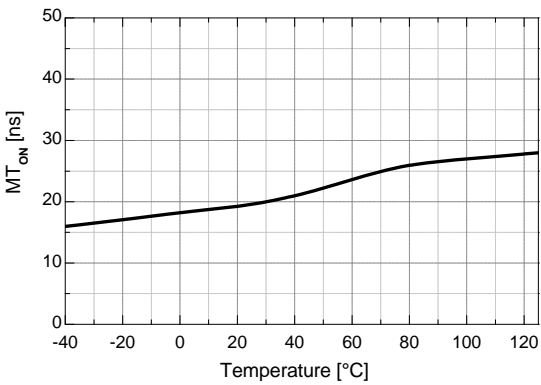


Figure 10. Turn-on Delay Matching vs. Temperature

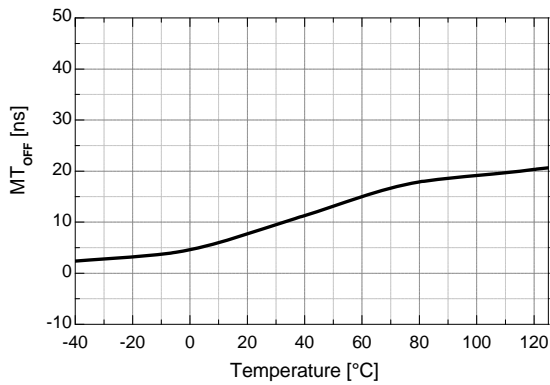


Figure 11. Turn-off Delay Matching vs. Temperature

Typical Characteristics (Continued)

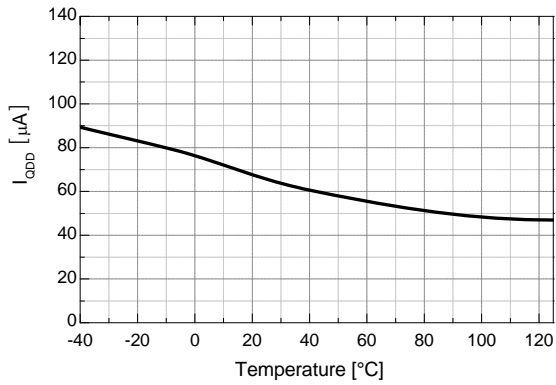


Figure 12. Quiescent  $V_{DD}$  Supply Current vs. Temperature

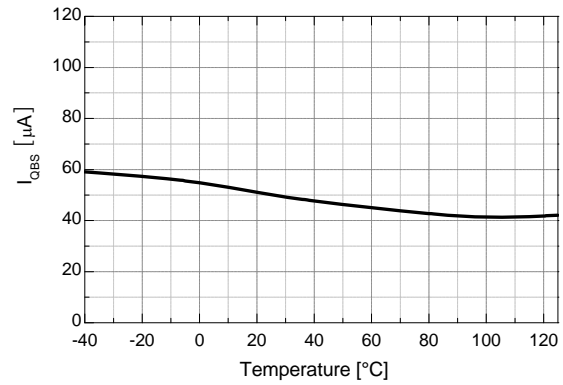


Figure 13. Quiescent  $V_{BS}$  Supply Current vs. Temperature

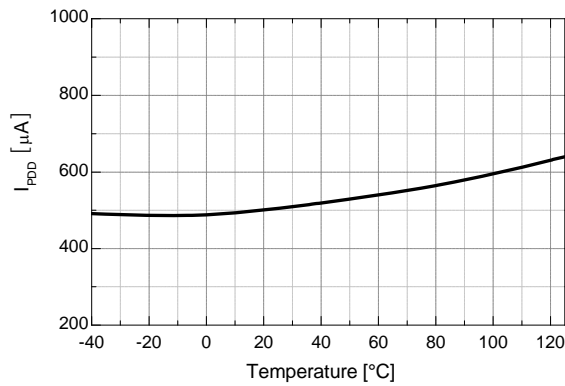


Figure 14. Operating  $V_{DD}$  Supply Current vs. Temperature

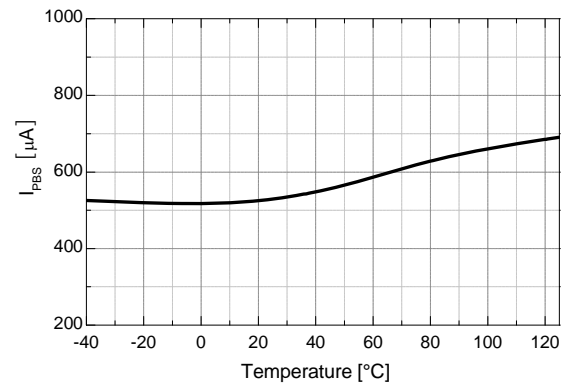


Figure 15. Operating  $V_{BS}$  Supply Current vs. Temperature.

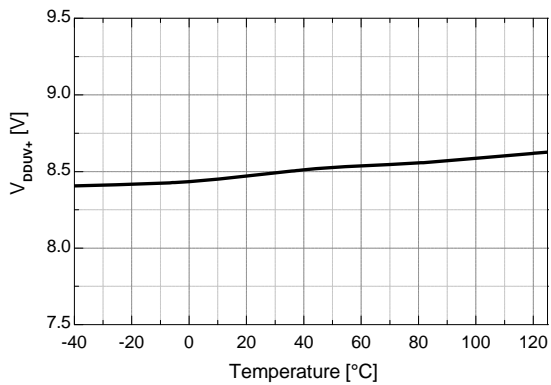


Figure 16.  $V_{DD}$  UVLO+ vs. Temperature

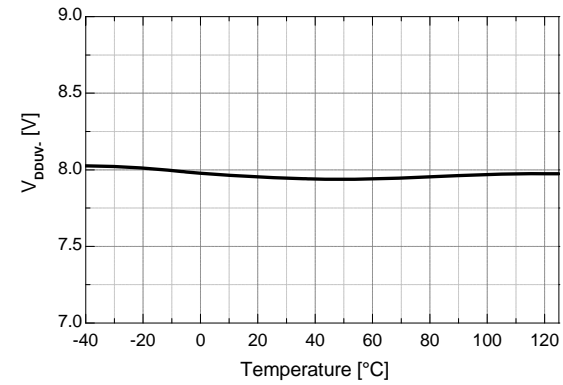
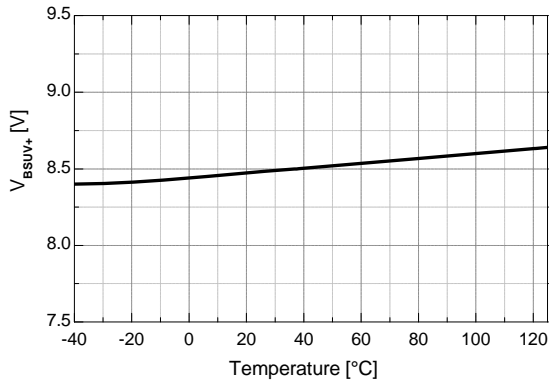


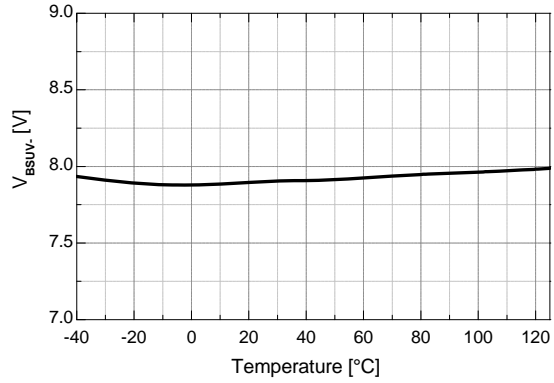
Figure 17.  $V_{DD}$  UVLO- vs. Temperature



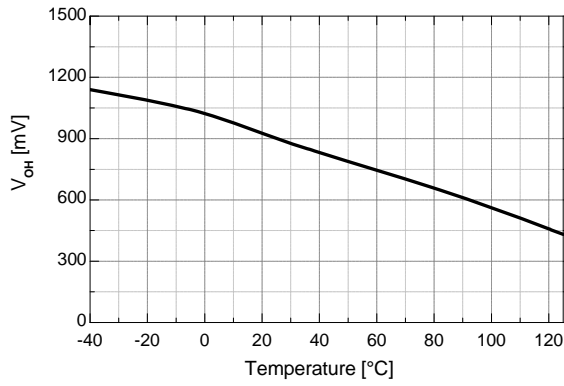
**Typical Characteristics** (Continued)



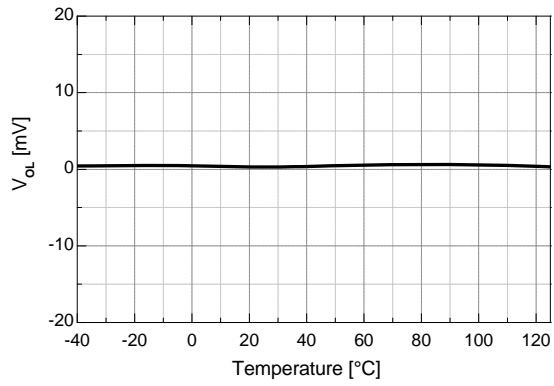
**Figure 18.  $V_{BS}$  UVLO+ vs. Temperature**



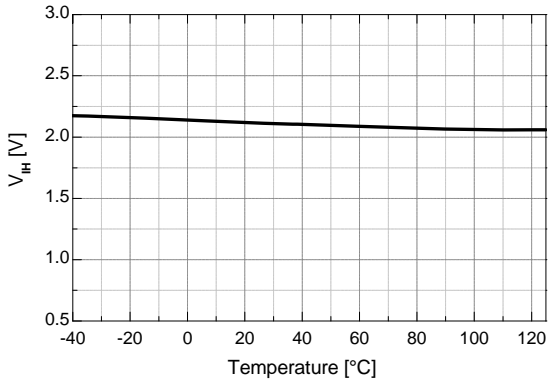
**Figure 19.  $V_{BS}$  UVLO- vs. Temperature**



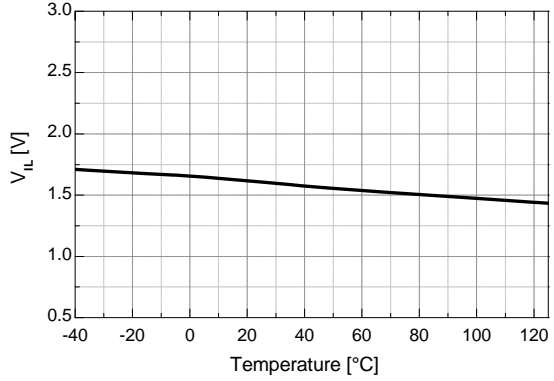
**Figure 20. High-Level Output Voltage vs. Temperature**



**Figure 21. Low-Level Output Voltage vs. Temperature**



**Figure 22. Logic High Input Voltage vs. Temperature**



**Figure 23. Low Input Voltage vs. Temperature**

Typical Characteristics (Continued)

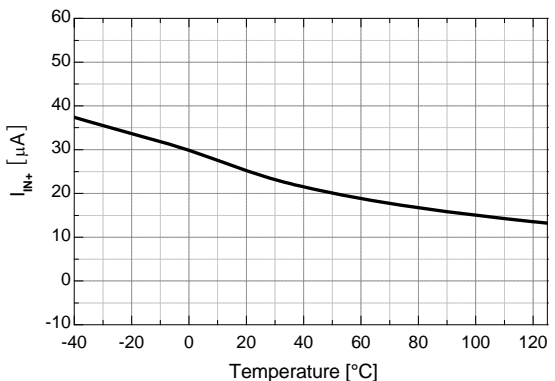


Figure 24. Logic Input High Bias Current vs. Temperature

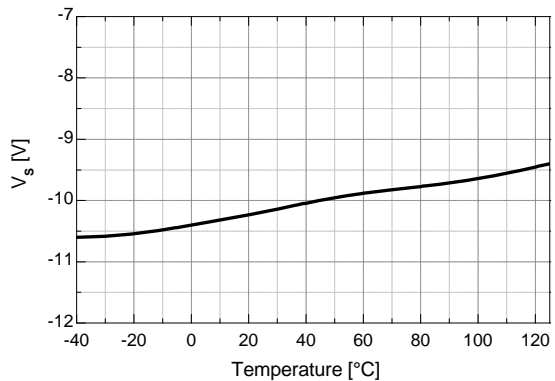


Figure 25. Allowable Negative  $V_S$  Voltage vs. Temperature

## Switching Time Definitions

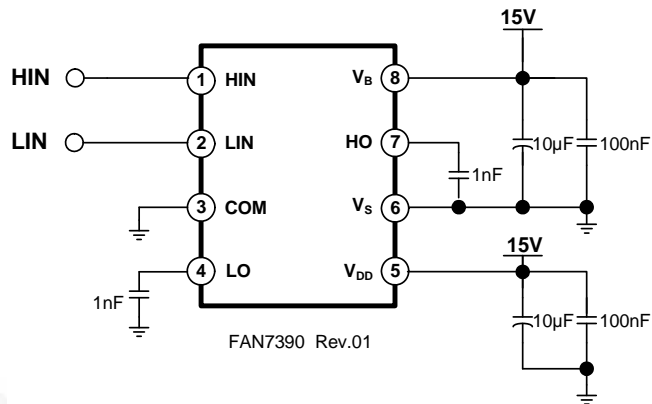


Figure 26. Switching Time Test Circuit (Referenced 8-SOP)

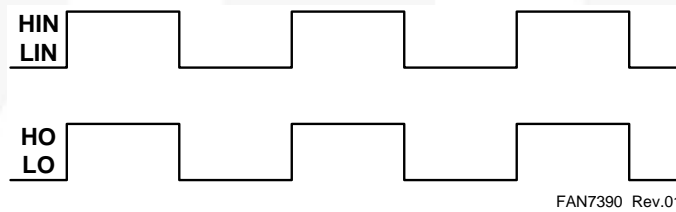


Figure 27. Input/Output Timing Diagram

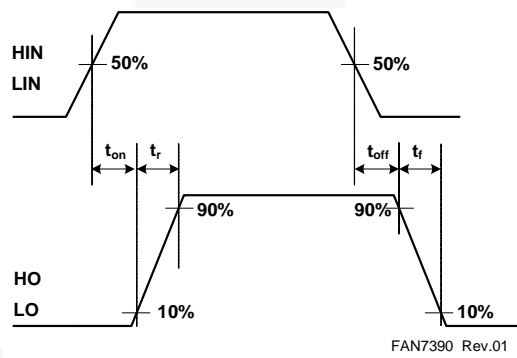


Figure 28. Switching Time Waveform Definitions

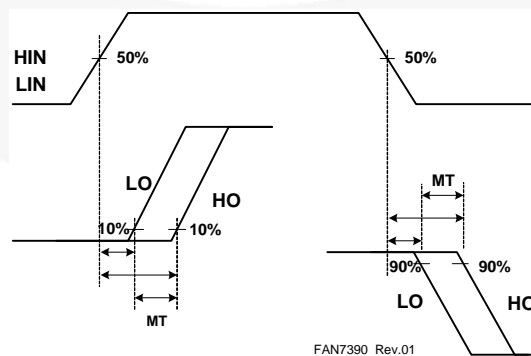


Figure 29. Delay Matching Waveform Definitions

Physical Dimensions

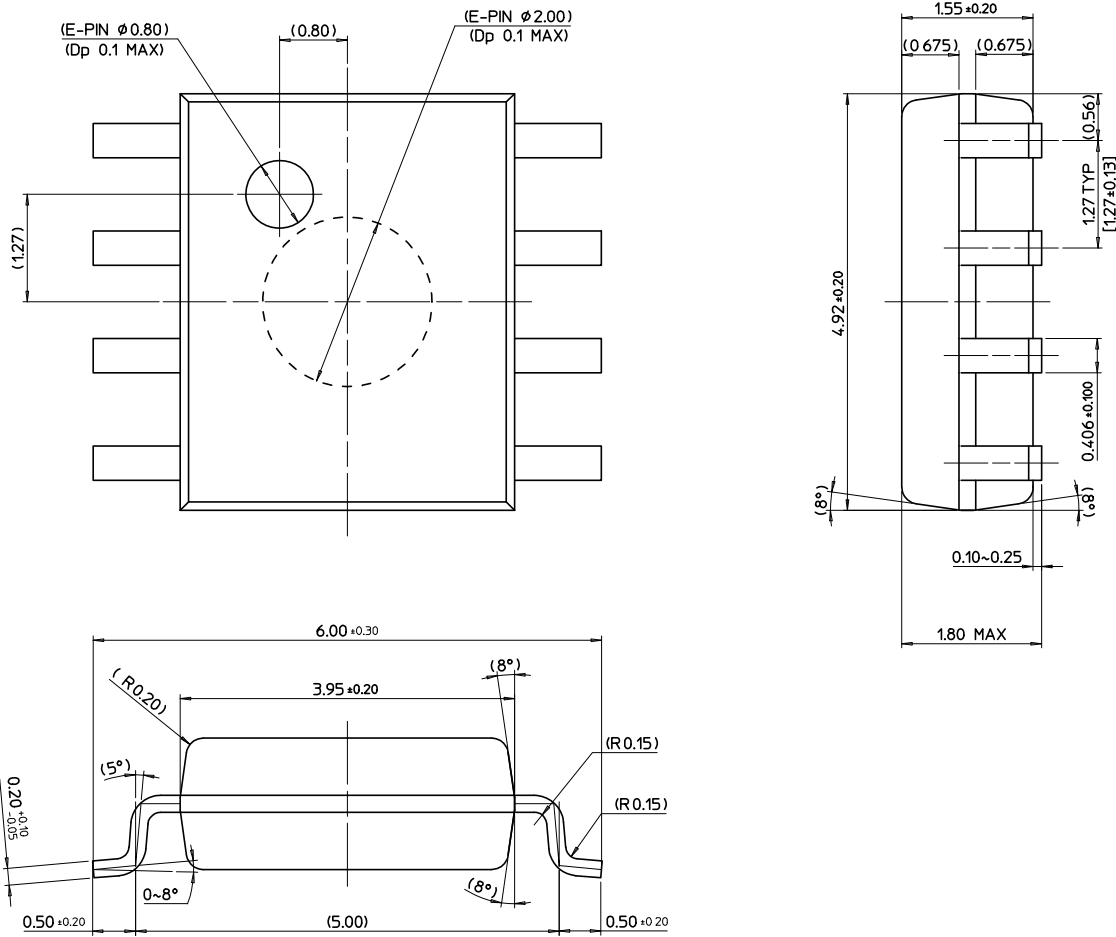


Figure 30. 8-Lead Small Outline Package (SOP)

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Physical Dimensions (Continued)

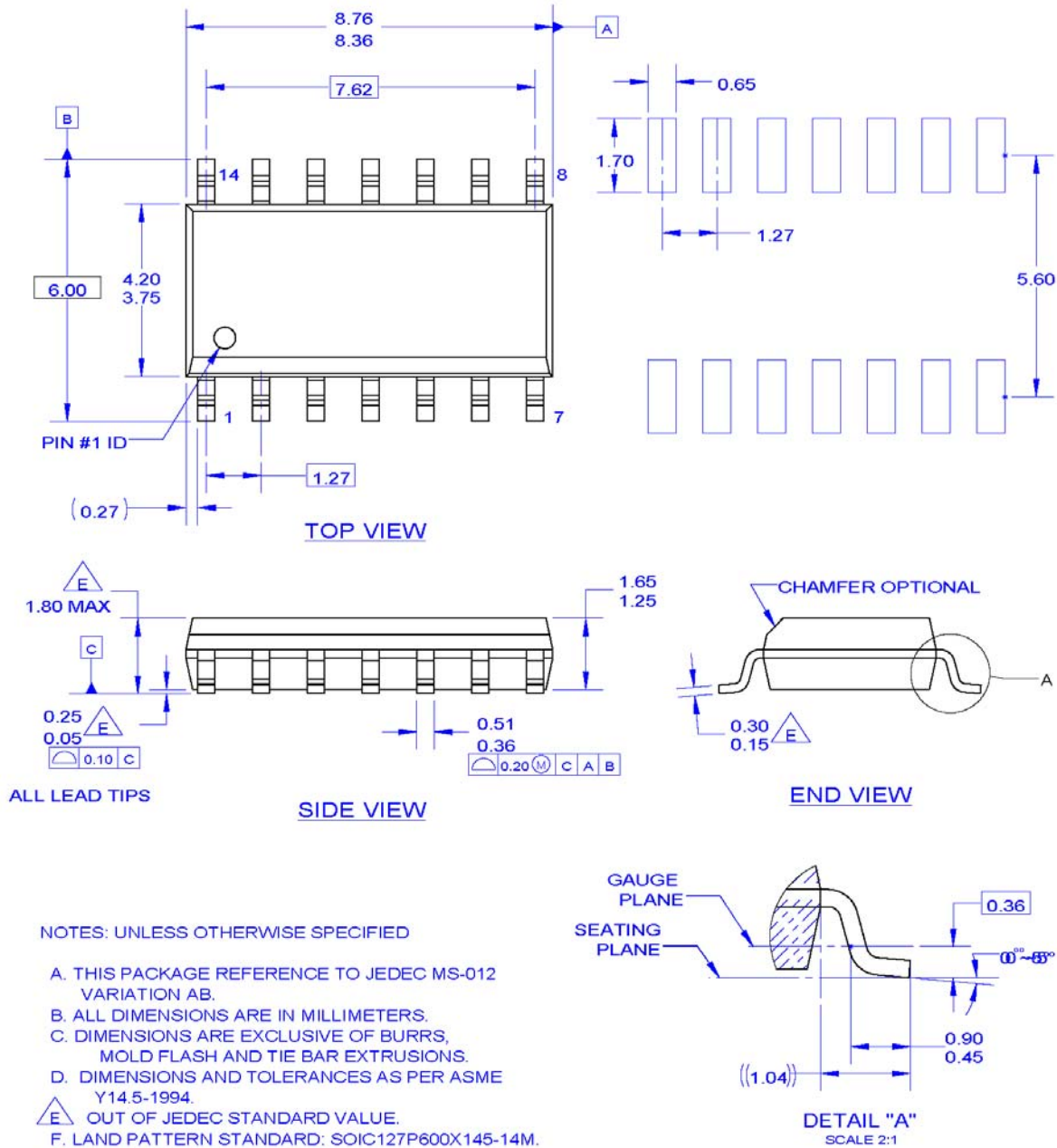


Figure 31. 14-Lead Small Outline Package (SOP)


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